
**Identification cards — Contactless
integrated circuit cards — Proximity
cards — Multiple PICCs in a single PCD
field**

*Cartes d'identification — Cartes à circuit(s) intégré(s) sans contact —
Cartes de proximité — Multiples PICCs dans le champ d'un seul PCD*

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Foreword

ISO (the International Organization for Standardization) and IEC (the International Electrotechnical Commission) form the specialized system for worldwide standardization. National bodies that are members of ISO or IEC participate in the development of International Standards through technical committees established by the respective organization to deal with particular fields of technical activity. ISO and IEC technical committees collaborate in fields of mutual interest. Other international organizations, governmental and non-governmental, in liaison with ISO and IEC, also take part in the work. In the field of information technology, ISO and IEC have established a joint technical committee, ISO/IEC JTC 1.

International Standards are drafted in accordance with the rules given in the ISO/IEC Directives, Part 2.

The main task of the joint technical committee is to prepare International Standards. Draft International Standards adopted by the joint technical committee are circulated to national bodies for voting. Publication as an International Standard requires approval by at least 75 % of the national bodies casting a vote.

In exceptional circumstances, when the joint technical committee has collected data of a different kind from that which is normally published as an International Standard ("state of the art", for example), it may decide to publish a Technical Report. A Technical Report is entirely informative in nature and shall be subject to review every five years in the same manner as an International Standard.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. ISO and IEC shall not be held responsible for identifying any or all such patent rights.

ISO/IEC TR 18268 was prepared by Joint Technical Committee ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and personal identification*.

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Introduction

Experience from the field has shown that the presence of multiple PICCs in a field can have unexpected results in terms of all PICCs being seen by the PCD and the quality of the communications. This Technical Report seeks to assemble the collective knowledge of the engineering principles involved.

This Technical Report is relevant to the standards listed in the Bibliography and an understanding of these is useful in placing this Technical Report in context.

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